



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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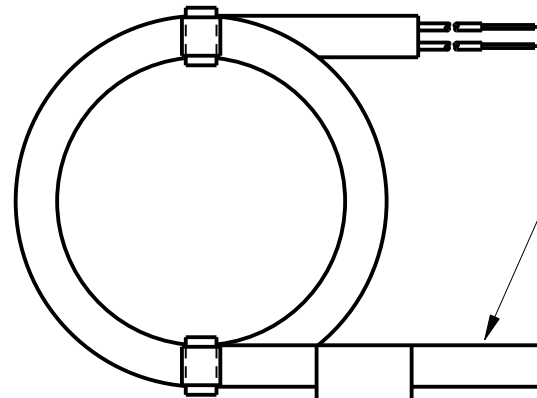
MICRO SWITCH
a Honeywell Division
FED. MFG. CODE 91929

**TEMPERATURE
SENSOR PROBE**

CATALOG LISTING
TD4S-L

TD4S-L
 CATALOG LISTING
 PAGE 1 OF 1
 ISSUE 2
 REVISIONS
 A 0000692
 JLH JUN03
 CHECK
 SAV 25JUN03
 CHECK
 JLH 25JUN03
 DRAWN
 PTC/CAD 2D

X90053-TD
 REPLACES
 DR-4230
 RELEASE NO.

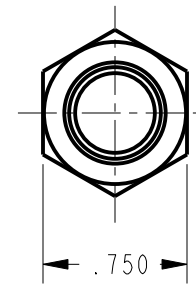


CABLE: BELDEN 9320 OR EQUIV.
.216 O.D.
SHIELDED TWIN LEAD
LENGTH: 3 FT. FROM
EXIT OF PROBE

THREADS: 1/4-18 NPTF
(6 THREADS MIN)

2.00

Ø .415



STRAIN RELIEF: HEYCO PART
NUMBER 3237
MATERIAL: PLASTIC-BLACK
OPERATING TEMPERATURE
LIMITS: -30 TO +100°C

ENCAPSULATION MATERIAL IS
A THERMALLY CONDUCTIVE EPOXY

RTV OVERCOAT APPLIED TO
INSULATE INTERCONNECT
PRIOR TO ENCAPSULATION

PROBE MATERIAL: TYPE 303 STAINLESS

NIFE TEMPERATURE SENSOR CHIP SPECIFICATIONS
GENERAL DESCRIPTION: AN INTEGRATED CIRCUIT CONSISTING OF A NIFE
THIN FILM RESISTANCE ELEMENT WITH A LASER TRIMMED SERIES LADDER

INTERCHANGEABILITY
(PACKAGE CHIP & 1mA MAX CURRENT)

TEMPERATURE	RESISTANCE (OHMS)
-30°C (-22°F)	1649±11 (1.7°C)
-20°C (-4°F)	1715±10 (1.5°C)
-10°C (14°F)	1784±9 (1.3°C)
0°C (32°F)	1854±8 (1.1°C)
+10°C (50°F)	1926±6 (0.8°C)
+20°C (68°F)	2000±5 (0.7°C)
+30°C (86°F)	2076±5 (0.7°C)
+40°C (104°F)	2153±6 (0.8°C)
+50°C (122°F)	2233±7 (0.9°C)
+60°C (140°F)	2314±9 (1.1°C)
+70°C (158°F)	2397±10 (1.2°C)
+80°C (176°F)	2482±12 (1.4°C)
+90°C (194°F)	2569±14 (1.6°C)
+100°C (212°F)	2658±16 (1.8°C)

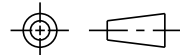
EQUATION FOR COMPUTING RESISTANCE:

$$R_T = R_0 + (3.84 \times 10^{-3} \times R_0 \times T) + (4.94 \times 10^{-6} \times R_0 \times T^2)$$

R_T = RESISTANCE AT TEMPERATURE T
 R_0 = RESISTANCE AT 0°C
 T = TEMPERATURE IN °C

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THIRD ANGLE PROJECTION



CHARACTERISTICS

OPERATING FORCE
DIFFERENTIAL FORCE
RELEASE FORCE
PRETRAVEL
DIFFERENTIAL TRAVEL
OVERTRAVEL
FREE POSITION

ELECTRICAL DATA

CONTACT ARRANGEMENT

SCALE FULL

DO NOT SCALE PRINT

UNLESS OTHERWISE SPECIFIED
TOLERANCES ARE

ONE PLACE	(.0)	±.030
TWO PLACE	(.00)	±.015
THREE PLACE	(.000)	±.005
ANGLES		±

WEIGHT

ANSI Y14.5M-1982 APPLIES